P-Channel 30 V (D-S) MOSFET



Marking code: N7

PRODUCT SUMMARY						
V _{DS} (V)	-30					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -10 \text{ V}$	0.088					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5 \text{ V}$	0.138					
Q _g typ. (nC)	4.1					
I _D (A) ^{a, b}	-3.5					
Configuration	Single					

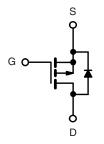
FEATURES

- TrenchFET® power MOSFET
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

· Load switch for portable devices



P-Channel MOSFET

ORDERING INFORMATION				
Package	SOT-23			
Lead (Pb)-free	Si2307CDS-T1-E3			
Lead (Pb)-free and halogen-free	Si2307CDS-T1-GE3			

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-source voltage		V_{DS}	-30	V	
Gate-source voltage		V_{GS}	± 20	V	
	T _C = 25 °C		-3.5		
Opation and during a support /T 150 90\ 9 h	T _C = 70 °C] . [-2.8	A	
Continuous drain current (T _J = 150 °C) ^{a, b}	T _A = 25 °C	l _D	-2.7 ^{a, b}		
	T _A = 70 °C		-2.2 ^{a, b}		
Pulsed drain current (10 µs pulse width)	I _{DM}	-12			
Ocalia a constanta di da consta h	T _C = 25 °C	I _S	-1.5		
Continuous source-drain diode current a, b	T _A = 25 °C		-0.91 ^{a, b}	i	
Maximum power dissipation ^{a, b}	T _C = 25 °C	P _D	1.8	W	
	T _C = 70 °C		1.14		
	T _A = 25 °C		1.1 ^{a, b}	- vv	
	T _A = 70 °C		0.7 ^{a, b}	1	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature)		260	1		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient a, c	t ≤ 5 s	R _{thJA}	90	115	°C/W
Maximum junction-to-foot (drain)	Steady state	R _{thJF}	55	70	C/VV

Notes

- a. Surface mounted on 1" x 1" FR4 board
- b. t = 5 s
- c. Maximum under steady state conditions is 166 °C/W

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-30	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	-32	-	m\//°C	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	4.5	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-1	-	-3	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	-100	nA	
Zana mata waltana alimba wa wali	1	V _{DS} = -30 V, V _{GS} = 0 V		-	-1	μA	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	-	-	-10	μΑ	
On-state drain current a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = -10 \text{ V}$	-6	-	-	Α	
Drain-source on-state resistance ^a	В	$V_{GS} = -10 \text{ V}, I_D = -3.5 \text{ A}$	-	0.073	0.088	Ω	
Dialii-Source oii-state resistance "	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -2.5 \text{ A}$	-	0.110	0.138		
Forward transconductance a	9 _{fs}	$V_{DS} = -10 \text{ V}, I_D = -3.5 \text{ A}$	-	7	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	340	-	pF	
Output capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	67	-		
Reverse transfer capacitance	C _{rss}		-	51	-		
Total gate charge	Qg		-	4.1	6.2	nC	
Gate-source charge	Q _{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -2.5 \text{ A}$	-	1.3	-		
Gate-drain charge	Q _{gd}		-	1.8	-		
Gate resistance	R_g	f = 1 MHz	-	10	-	Ω	
Turn-on delay time	t _{d(on)}		-	40	60		
Rise time	t _r	V_{DD} = -15 V, R_L = 15 Ω	-	40	60		
Turn-off delay time	t _{d(off)}	$I_D\cong$ -1 A, $V_{GEN}=$ -4.5 V, $R_g=$ 1 Ω	-	20	40		
Fall time	t _f		-	17	30	no	
Turn-on delay time	t _{d(on)}		-	5.5	10	ns	
Rise time	t _r	V_{DD} = -15 V, R_L = 15 Ω	-	13	25		
Turn-off delay time	t _{d(off)}	$I_D\cong$ -1 A, $V_{GEN}=$ -10 V, $R_g=$ 1 Ω	-	17	30		
Fall time	t _f			7.7	15		
Drain-Source Body Diode Characteris	tics						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	-1.5	Α	
Pulse diode forward current	I _{SM}		-	-	-12] ^	
Body diode voltage	V_{SD}	I _S = -0.75 A, V _{GS} = 0 V	-	-0.8	-1.2	V	
Body diode reverse recovery time	t _{rr}		-	17	30	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = -2.5 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	11	20	nC	
Reverse recovery fall time	t _a	T _J = 25 °C	-	12	-		
Reverse recovery rise time	t _b		-	5	-	ns	

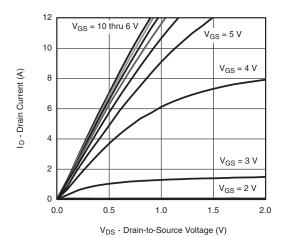
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing

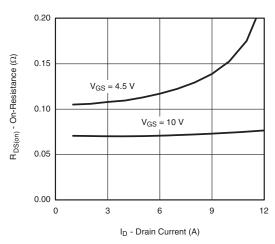
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



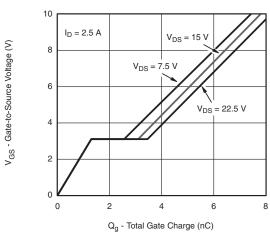
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



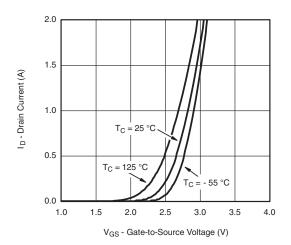
Output Characteristics



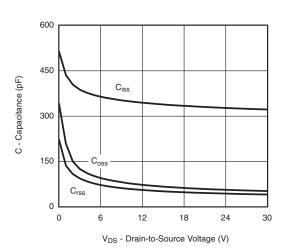
On-Resistance vs. Drain Current and Gate Voltage



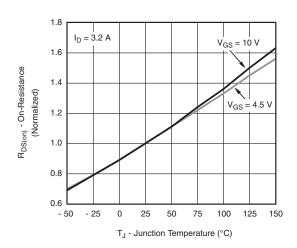
Gate Charge



Transfer Characteristics



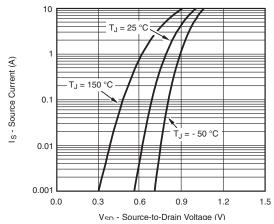
Capacitance



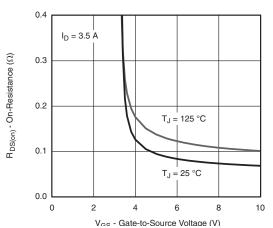
On-Resistance vs. Junction Temperature



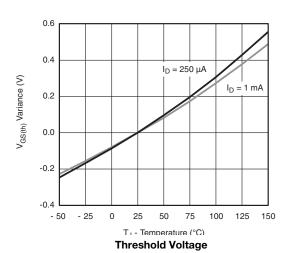
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

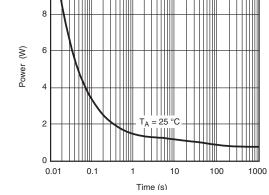


Source-Drain Diode Forward Voltage

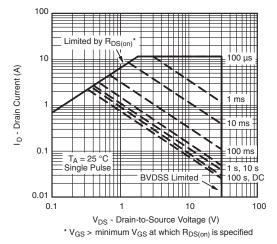


On-Resistance vs. Gate-to-Source Voltage





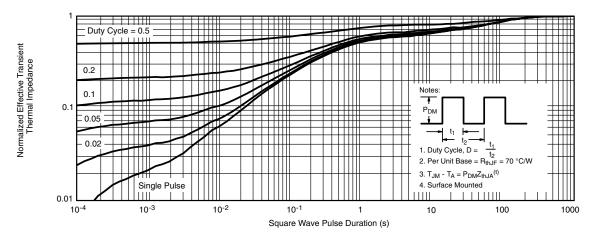
Single Pulse Power, Junction-to-Ambient



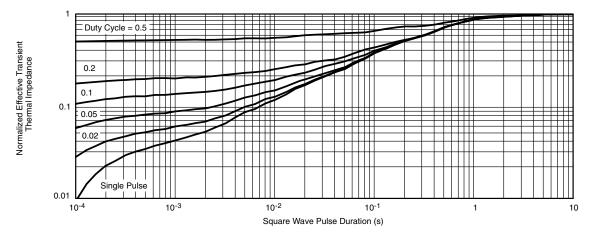
Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



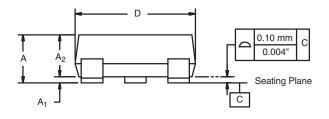
Normalized Thermal Transient Impedance, Junction-to-Foot

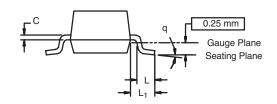
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SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K. 09-	Jul-01				

DWG: 5479

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RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE

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